







Electronics Assembly

UV Light-Curable Adhesives, Coatings,
and Encapsulants for Electronic Assembly

CONFORMAL COATINGS

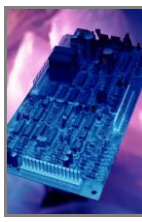
Reliable Board Protection in Seconds

Product Number*	Description	Nominal Viscosity (cP)	Durometer Hardness	Modulus of Elasticity MPa [psi]	Dielectric Strength (Volts/mil)	Approvals	Halogen-Free?
9481-E	<ul style="list-style-type: none"> Secondary moisture cure for shadowed areas Highest chemical and abrasion resistance Low viscosity for thin coatings 	125	D75	150 [21,800]	>1,500	MIL-I-46058C listed IPC-CC-830B approved UL recognized	
984-LVUF	<ul style="list-style-type: none"> Isocyanate free Rigid for high chemical and abrasion resistance Secondary heat cure for shadowed areas 	150	D80	410 [60,000]	1,800 @ 2 mil	MIL-I-46058 listed IPC-CC-830 approved UL recognized	
987	<ul style="list-style-type: none"> Isocyanate free High chemical and abrasion resistance Secondary heat cure for shadowed areas 	150	D85	900 [130,000]	>1,500 @ 1 mil	MIL-I-46058 listed IPC-CC-830 approved	
9-20351-UR	<ul style="list-style-type: none"> Isocyanate free Easy one-pass coverage of high-profile leads and tall components without seeping into shadow areas Secondary heat cure for shadowed areas 	14,500	D60	24 [3,500]	-	-	
9-20557	<ul style="list-style-type: none"> Isocyanate free Medium viscosity for wetting components Low modulus for thermal cycling performance Secondary heat cure for shadowed areas 	2,500	D60	240 [35,000]	1,200 @ 2 mil	MIL-I-46058C listed IPC-CC-830 approved UL recognized	
9-20557-LV	<ul style="list-style-type: none"> Isocyanate free Low viscosity for thin coatings Low modulus for enhanced thermal cycling performance Secondary heat cure for shadowed areas 	850	D70	240 [35,000]	>1,500 @ 1 mil	MIL-I-46058C listed IPC-CC-830 approved	

*Other grades are available for specific applications requiring physical properties different from standard products listed here.
NOTE: Consult DYMAX Conformal Coating Validation Report for more detailed information on conformal coatings.



Black Coatings



Fluorescing Coatings



Clear Coatings

- Solvent free
- Tack-free UV cures in seconds
- Excellent environmental resistance
- Black grades available
- Adhesion to flex circuit substrates (FPC)
- Low stress under thermal cycling
- Rigid and flexible coatings available
- Electrically insulating

Environmental Benefits of DYMAX Light-Curable Materials

DYMAX understands that safe ecologically friendly products benefit our customers, the environment, and us. We have created materials with attributes that lower products costs, life-cycle costs, and ecological impact. These attributes include:

- Solvent-free materials
- Halogen-free materials
- RoHS compliance
- REACH - no substance of very high concern (SVHC)
- Eco-friendly, one-component materials




DYMAX Halogen-Free conformal coatings, encapsulants, and adhesives are documented by an independent laboratory to meet or exceed standards set forth in IEC 61249-2-21. This international directive defines halogen-free as <900 ppm for chlorine, <900 ppm for bromine and < 1500 ppm total level of both combined. The current test method used for certification is BS EN 14582:2007.



THERMAL INTERFACE ADHESIVES

Efficient Thermal Transfer Between Heat Sinks and Electronics

Product Number	Description	Applications	Thermal Conductivity	Nominal Viscosity (cP)	Halogen-Free?
9-20801	<ul style="list-style-type: none"> Light cure in seconds Secondary activator or heat cure for shadowed areas* Highly thixotropic for optimal placement 	<ul style="list-style-type: none"> Mounting heat sinks on PCBs LED heat dissipation 	0.9 W/m*K	110,000	

*DYMAX 501-E is the recommended activator for shadowed areas







Bonding Heat Sinks

- Sets in seconds with light exposure
- Cure shadow areas with activator or heat
- High-strength bonds
- Low stress for mismatched CTE's
- Room-temperature storage and cure

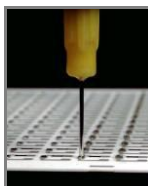
CHIP ENCAPSULANTS and WIRE BONDRERS

For Superior Protection on Flexible and Rigid Platforms

Product Number	Description	Applications	Durometer Hardness	Nominal Viscosity (cP)	Elongation at Break (%)	Modulus of Elasticity MPa [psi]	Halogen-Free?
9001-E-v3.1	<ul style="list-style-type: none"> UV/visible light cure for fastest processing Secondary heat cure for shadowed areas Multiple viscosities available for optimal flow and coverage Low modulus for wire bonding 	<ul style="list-style-type: none"> Chip-on-board Chip-on-flex Chip-on-glass Wire bonding Bare-die encapsulation 	D45	4,500	150	17 [2,500]	
9001-E-v3.5				17,000			
9001-E-v3.7				50,000			
9008	<ul style="list-style-type: none"> Flexible Highly moisture-resistant bonds to diverse surfaces such as polyimide, DAP, glass, epoxy board, metal, PET High adhesion, even at -40°C [-40°F] 	<ul style="list-style-type: none"> Chip-on-flex encapsulation Flex circuit bonding and attachment to PCB and glass 	A85	4,500	300	-	



Black Encapsulants



Chip Encapsulants




Flex Circuit Encapsulants

- 100% solvent free
- Instant UV/visible cures
- High ionic purity
- Tenacious adhesion to flex circuit substrates (polyimide and PET)
- Low stress under thermal cycling
- Electrically insulating
- Room-temperature storage
- Thermal shock and moisture resistance

WIRE TACKING

Photocurable Technology Offers Lower Costs and Increased Productivity

Product Number	Description	Nominal Viscosity (cP)	Durometer Hardness	Tensile @ Break MPa [psi]	Halogen-Free?
9-911 Rev A	<ul style="list-style-type: none"> On-demand cure for optimal positioning Exposed areas cure in seconds for immediate strength 	36,000	D80	21 [3,000]	




Wire Tacking

- Instant UV cure
- One part
- Solvent free
- Unlimited pot life
- Fluorescing additive for in-line quality control
- Excellent adhesion to solder masks and wires
- Thermal shock and moisture resistance

RUGGEDIZATION

Photocurable Technology Offers Lower Costs and Increased Productivity

Product Number	Description and Applications	Nominal Viscosity (cP)	Durometer Hardness	Tensile @ Break MPa [psi]	Cure Depth mm [in]	Halogen Free?
9422-SC	<ul style="list-style-type: none"> Highly thixotropic for optimal placement and wetting of components See-Cure version for easy visual confirmation of full cure 	37,500	D50	16 [2,300]	6.5 [0.26]	



Ruggedizing





Leadless Component Ruggedization

- Fast dispense and cure
- Pre- or post-reflow, room-temperature application
- Reduce stress on interconnects during push, pull, shock, drop, and vibration
- Easy rework
- Simple visual inspection
- Improved bond strength for die and pry testing
- Engineered bead shape for wetting both board surface and component edge without seeping into shadowed area

ACRYLATED URETHANE POTTING and SEALING

For Shallow Potting in 10-30 Seconds or Less – Highest Adhesion to Substrates

Product Number	Description and Applications	Recommended Substrates	UV Cure* Speed (sec)/ Depth (mm [in])	Durometer Hardness	Nominal Viscosity (cP)	Halogen-Free?
921-T	<ul style="list-style-type: none"> Connectors, thermal switches Tamperproofing Translucent bonds with high adhesion 	ABS, filled nylon, metal, glass	30/6.4 [.025]	D75	3,500	
921-VT					11,000	
921-Gel					25,000	
9001-E V3.1	<ul style="list-style-type: none"> Sensors Flexible Excellent adhesion to engineering plastics 	ABS, PC, PVC, FR-4, metals	15/6.4 [0.25]	D45	4,500	
9001-E V3.5					17,000	
9001-E V3.7					50,000	

*UV cure speed depends on the intensity reaching the surface of the resin. Cure speed was measured at an intensity of 175 mW/cm².



Cable Potting



Deep Layer Potting




Chip Potting



- Full UV/visible cure in seconds
- Solvent free
- High adhesion to substrates
- Flexible and rigid products available

LED ENCAPSULATING

Bonding, Potting, and Sealing in Seconds

Product Number	Description	Applications	Linear Shrinkage (%)	Nominal Viscosity (cP)	Halogen-Free?
LIGHT CAP® 9622	<ul style="list-style-type: none"> UV/visible light cure in seconds No mixing required Heat resistant to 100°C Resistant to long-term UV exposure High light transmittance Durometer between silicone and epoxy 	<ul style="list-style-type: none"> Instant casting of LEDs Rapid forming of protective optical lens 	0.8	12,000	

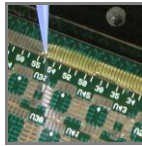
REMOVABLE MASKS

Product Number	Description and Applications	Cure Depth (mm [in])	Durometer Hardness	Cure Speed* (sec)	Viscosity (cP)	Halogen-Free?
9-20479-B	<ul style="list-style-type: none"> Peelable Wave-solder resistant Blue Excellent viscosity for machine dispensing 	6.4 [0.25]	A70	10	150,000	
9-318-F	<ul style="list-style-type: none"> Peelable Fluoresces for easy inspection Very fast curing 	6.4 [0.25]	A55	<4	50,000	

*Cure speed depends on the intensity and distance from the light source. Cure speed was measured at an intensity of 175 mW/cm².



Fluorescing Mask





Removable Mask



Peelable Mask

- 100% solids
- UV/visible cure in seconds
- No ionic contamination
- Fluorescing and blue grades
- One part

DISPLAY OPTICAL BONDING and LAMINATING

Product Number	Description	Applications	Linear Shrinkage (%)	Nominal Viscosity (cP)	Halogen-Free?
9-20737	<ul style="list-style-type: none"> High viscosity for filling gap without flowing into shadowed areas Adhesion to various frame substrates 	Sealing frame to display surface	TBD	11,000	
9641-LV	<ul style="list-style-type: none"> Optimized cure speed and modulus for low stress bond Enhanced resistance to yellowing from heat or UV exposure Optically clear 	Optical bonding of touch screens and protective cover windows	4%	1,100	



LCD Laminating Plastics with 9641-LV

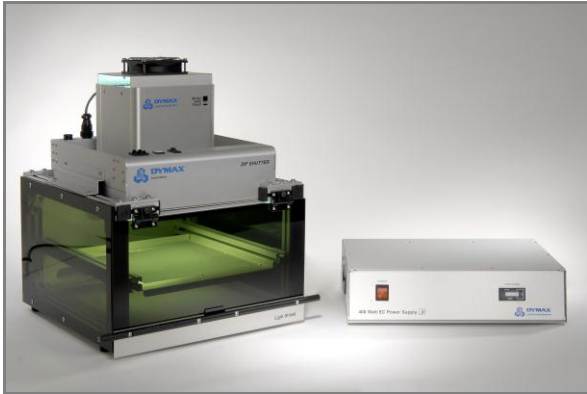


Touch Screen or Cover Window Optical Bonding

- One component, no mixing required
- Fast cure
- Flexible
- Bonds various substrates
- Resistant to yellowing
- High optical clarity

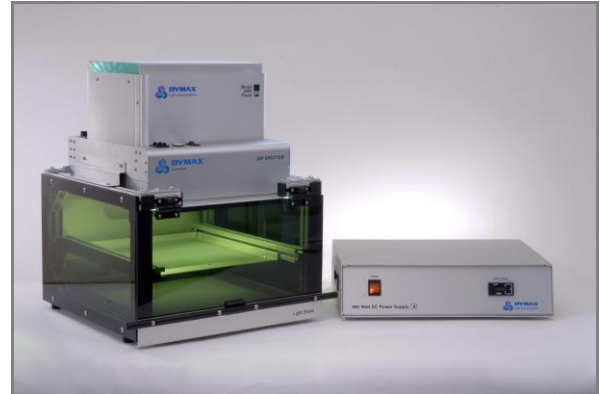
Flood Chambers and Conveyor Curing Systems for Electronic and Photonic Applications

Successful UV processing demands that the curing equipment be matched to the resin to optimize both performance and cost savings. DYMAX manufactures UV resins and UV curing equipment and specializes in the optimization of UV curing processes. Our technical specialists are ready to help you optimize your process, and maximize your profit and product performance. For resin and equipment selection assistance please contact DYMAX Applications Engineering.



DYMAX 5000 Flood Lamp Systems
Most Popular and Versatile

Ideal for potting, sealing, and encapsulating applications



DYMAX 2000 Flood Lamp Systems
Largest Cure Area

Ideal for LED and masking applications



**DYMAX UVCS Series UV Curing
Conveyor Systems with 5000-EC Lamps**

Ideal for conformal coating applications



**DYMAX Heavy-Duty UV Curing
WIDECURE™ Conveyor Systems**

Ideal for curing adhesives, coatings, and inks

UV Light Curing Spot Lamps for Electronic and Photonic Applications



DYMAX BlueWave® 200 UV Curing Spot Lamp
Ideal for fastest processing of small curing areas



DYMAX BlueWave® LED Prime UVA
Visible Spot Light Curing System
Ideal for cool spot curing coatings



Liquid Lightguides
Come in an assortment of sizes and
split wand configurations



ACCU-CAL 50™ Radiometer
Ideal for process monitoring



Reduced environmental impact and energy conservation are core pillars of the DYMAX mission. Over the last 30 years, DYMAX light-curable materials and curing equipment have become the industry standard for fast, environmentally conscious assembly. DYMAX products are readily replacing technologies that contain hazardous ingredients, produce waste, or require higher amounts of energy to process. DYMAX understands that safe ecologically friendly products benefit our customers, the environment, and us. We have created materials with attributes that lower product costs, life-cycle costs, and ecological impact.

DYMAX Eco underlines the DYMAX commitment to the environment. Information for Environmental Health and Safety officers, government officials, and engineers to assist in making informed decisions when comparing assembly processes is available by visiting www.dymax.com/eco.

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